

Listing of Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

1.(Currently Amended) A capacitor comprising:

 a non-segmented electrically conductive plate;

 an electrically conductive segmented plate defining at least two electrically conductive plate segments disposed over the non-segmented electrically conductive plate;

 a first capacitor dielectric disposed between the non-segmented electrically conductive plate and the segmented electrically conductive plate;

 at least one electrically conductive interconnect coupling one of the at least two plate segments to the non-segmented electrically conductive plate; and

 a second capacitor dielectric disposed between the at least two plate segments;

wherein one of the at least two electrically conductive plate segments is thinner than the other one.

2.(Canceled)

3.(Currently Amended) The capacitor according to claim 2 1, wherein the thinner plate segment is coupled to the non-segmented electrically conductive plate by the at least one interconnect.

4.(Original) The capacitor according to claim 1, wherein the second capacitor dielectric has a high dielectric constant.

5.(Original) The capacitor according to claim 1, wherein the at least two plate segments form a lateral capacitor.

6.(Original) The capacitor according to claim 1, wherein the at least one electrically conductive interconnect extends through the first capacitor dielectric.

7.(Original) The capacitor according to claim 1, wherein the plate and one of the at least two plate segments are each of a first electrical bias, and the other one of the at least two plate segments is of a second electrical bias opposite to the first electrical bias.

8.(Original) The capacitor according to claim 1, wherein the capacitor comprises a metal-insulator-metal capacitor.

9.(Currently Amended) A capacitor comprising:

 a non-segmented electrically conductive plate;

 an electrically conductive segmented plate defining a first plurality of

 electrically conductive plate segments and a second plurality of electrically conductive plate segments, the first and second plurality of electrically conductive plate segments disposed over the non-segmented electrically conductive plate;

a first capacitor dielectric disposed between the non-segmented electrically conductive plate and the segmented electrically conductive plate; at least one electrically conductive interconnect coupling each of the plate segments of one of the first and second plurality of plate segments to the non-segmented electrically conductive plate; and a second capacitor dielectric disposed between the plate segments; wherein the plate segments of one of the first and second plurality of electrically conductive plate segments are thinner than the plate segments of the other one.

10.(Canceled)

11.(Currently Amended) The capacitor according to claim 10 9, wherein the thinner plate segments are coupled to the non-segmented electrically conductive plate by the at least one interconnects.

12.(Original) The capacitor according to claim 9, wherein the second capacitor dielectric has a high dielectric constant.

13.(Original) The capacitor according to claim 9, wherein the first and second plurality of plate segments form lateral capacitors.

14.(Original) The capacitor according to claim 9, wherein the first plurality of plate segments alternate with the second plurality of plate segments.

15.(Original) The capacitor according to claim 9, wherein the at least one electrically conductive interconnects extend through the first capacitor dielectric.

16.(Original) The capacitor according to claim 9, wherein the plate and one of the first and second plurality of plate segments are each of a first electrical bias, and the other one of the first and second plurality of plate segments are of a second electrical bias opposite to the first electrical bias.

17.(Original) The capacitor according to claim 9, wherein the capacitor comprises a metal-insulator-metal capacitor.

18.(Currently Amended) A method of fabricating a capacitor, comprising:

forming a non-segmented electrically conductive plate;

forming a first capacitor dielectric over the non-segmented electrically

conductive plate;

forming at least one via in the first capacitor dielectric;

forming an electrically conductive segmented plate over the first capacitor

dielectric, the segmented electrically conductive plate defining at least two

electrically conductive plate segments, one of the at least two electrically

conductive plate segments being thinner than the other one, the at least one via

electrically coupling one of the at least two plate segments to the non-segmented electrically conductive plate; and

forming a second capacitor dielectric between the at least two plate segments.

19.(Original) The method according to claim 18, wherein the capacitor comprises a metal-insulator-metal capacitor.

20.(Currently Amended) A method of fabricating a capacitor, comprising:

forming a non-segmented electrically conductive plate;

forming a first capacitor dielectric over the non-segmented electrically conductive plate;

forming a plurality of vias in the first capacitor dielectric;

forming an electrically conductive segmented plate over the first capacitor dielectric, the segmented electrically conductive plate defining a first plurality of electrically conductive plate segments and a second plurality of electrically conductive plate segments, the plate segments of one of the first and second plurality of electrically conductive plate segments being thinner than the plate segments of the other one, the vias electrically coupling the conductive plate segments of one of the first and second plurality of plate segments to the non-segmented electrically conductive plate; and

forming a second capacitor dielectric between the plate segments.

21.(Original) The method according to claim 20, wherein the capacitor comprises a metal-insulator-metal capacitor.

22.(Currently Amended) A capacitor comprising:

an electrically conductive plate;

an electrically conductive segmented plate defining at least two electrically conductive plate segments disposed over the electrically conductive plate;

a first capacitor dielectric disposed between the electrically conductive plate and the segmented electrically conductive plate;

at least one electrically conductive interconnect coupling one of the at least two plate segments to the electrically conductive plate; and

a second capacitor dielectric disposed between the at least two plate segments and extending perpendicular to the first capacitor dielectric,
wherein one of the at least two electrically conductive plate segments being
thinner than the other one.